PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5537928

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
GAKU IMAMURA	02/05/2019
GENKI YOSHIKAWA	02/05/2019
TAKASHI WASHIO	02/01/2019

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16463585

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DATE SIGNED:	05/23/2019

Total Attachments: 2
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Patent

ASSIGNMENT

WHEREAS WE, the below named inventors, (hereinafter referred to as "Assignors"), have made an invention entitled:

SAMPLE IDENTIFICATION METHOD BASED ON CHEMICAL SENSOR MEASUREMENT, SAMPLE IDENTIFICATION DEVICE, AND INPUT PARAMETER ESTIMATION METHOD

for which WE filed PCT/JP2017/042060 on November 22, 2017; and

WHEREAS **NATIONAL INSTITUTE FOR MATERIALS SCIENCE** whose post office address is **2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki 3050047, Japan** (hereinafter referred to as "Assignee"), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Director of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, WE have hereunto set my hands.

Full Name of first Assignor	**Gaku IMAMURA**
Address	c/o NATIONAL INSTITUTE FOR MATERIALS SCIENCE, 2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki 3050047, Japan
Signature	
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Full Name of second Assignor	**Genki YOSHIKAWA**
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Signature	
Date	February 5th. 2019

Full Name of first Assignor	Takashi WASHIO
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Date	February, 1, 2019